



Neutron Irradiation for P-type Sensors. Detector Characterization with ALIBAVA system

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Outline

- I. Fabrication process
- II. P-type μ strip detectors irradiated with neutrons
- III. Setup (ALIBAVA system)
- IV. Detectors (IV-QV)
- V. Microdischarges
- VI. Summary

I. Fabrication Process

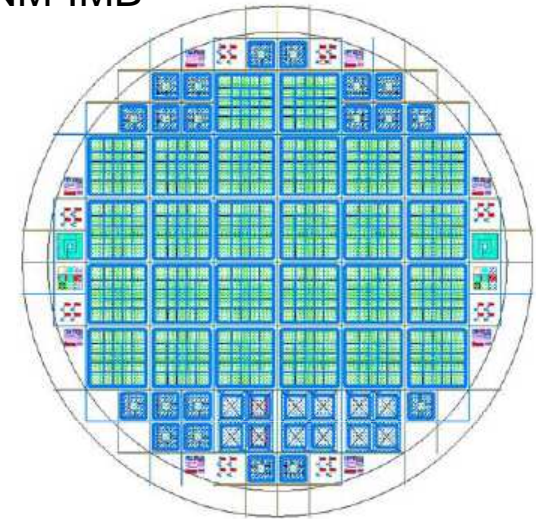
□ Detectors have been fabricated in the Clean Room facility of CNM-IMB

□ Rd50 Mask

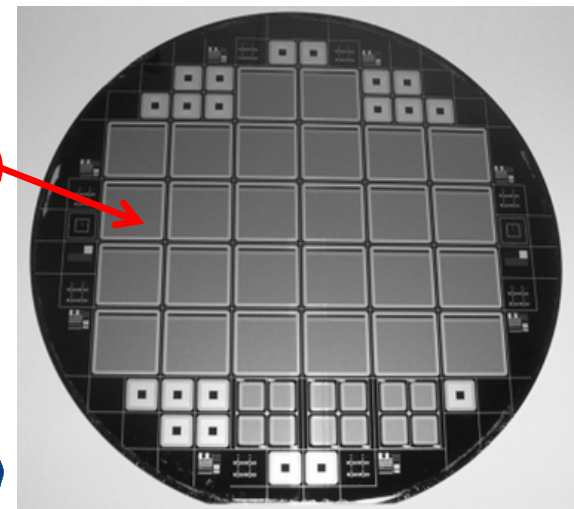
- Designed by the RD50 Collaboration
- Double side processing
- One metal layer

□ Structures

- 26 microstrips detectors
 - Polysilicon biasing resistors
 - Capacitive coupling
 - P-spray insulation
 - No p-stops
- 20 pad detectors
- 12 pixel detectors
- 8 test structure sets



microstrips detectors
used for this work

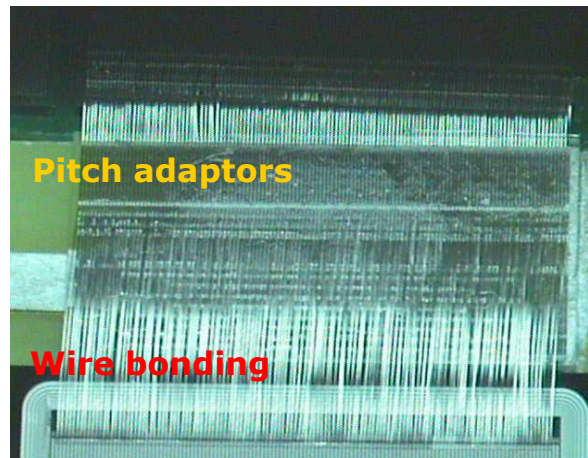
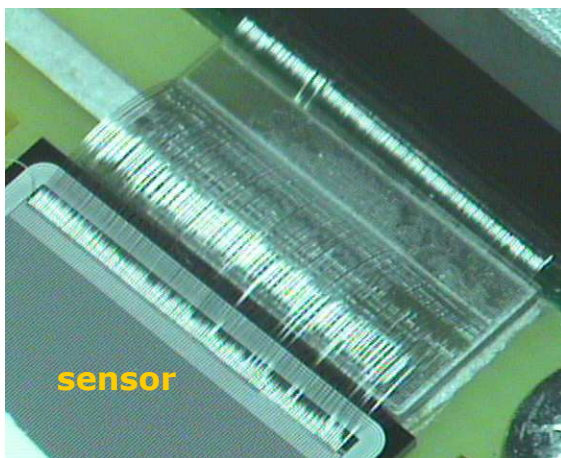


II. P-type μ strip detectors irradiated with neutrons

- Area: 1x1 cm²
- 130 strips, width: 32 μ m
- Pitch: 80 μ m
- Thickness: 300 μ m
- Multiple guard ring
- Surface isolation: p-spray

- ▣ FZ, MCz substrates to evaluate
- ▣ 1 MeV equivalent neutron irradiation at TRIGA nuclear reactor in Ljubljana, Slovenia.
- ▣ No annealing (except while wire bonding, ~2h)

Wire bonding



FLUENCES
1×10^{14} n/cm ²
3×10^{14} n/cm ²
1×10^{15} n/cm ²
3×10^{15} n/cm ²
8×10^{15} n/cm ²

III. ALIBAVA system

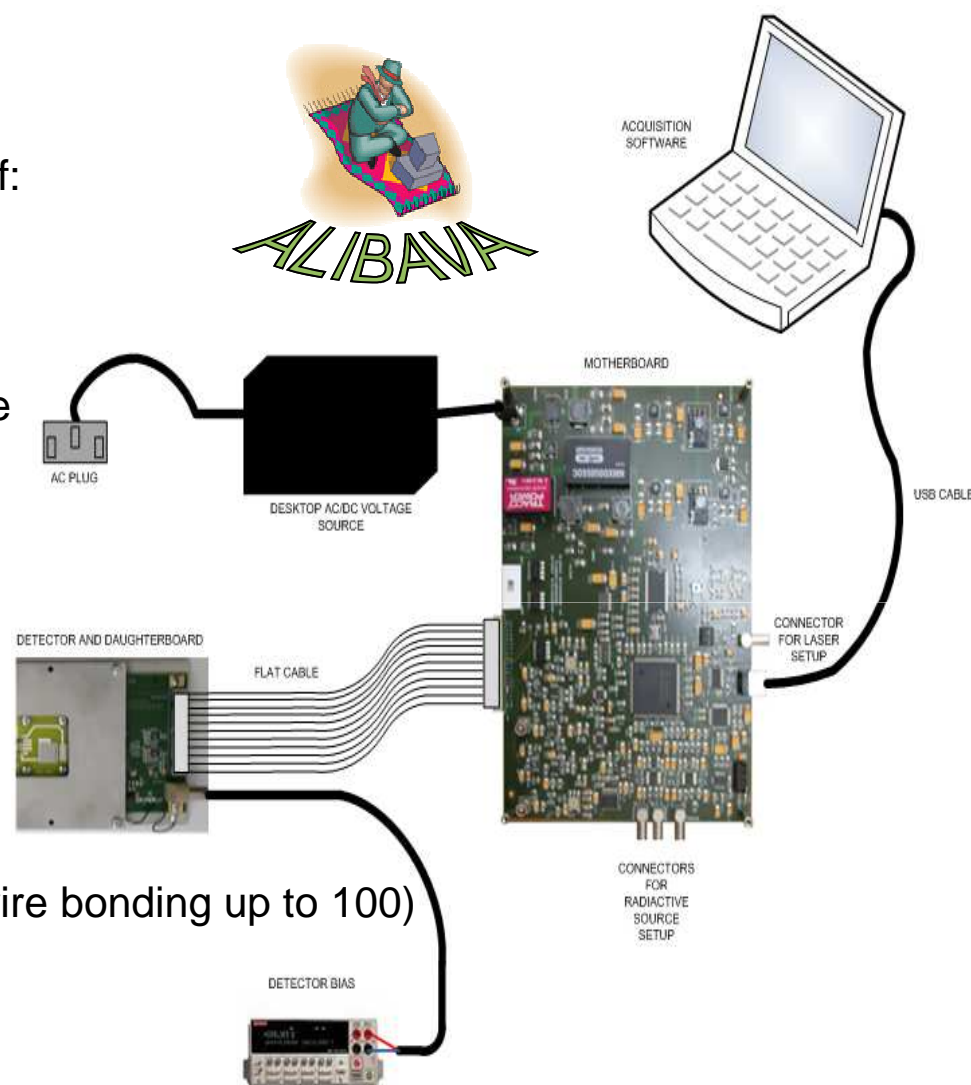
□ Compact and portable system consisting of:

➤ Mother Board (MB):

- Controls the hardware part
- Processes de trigger signals and the analogue data
- Communicates with a PC via USB

➤ Daughter Board (DB)

- Two Beetle chips in parallel mode
- 256 input channels (128 per chip)
- 3 types of pitch adaptors (multiple wire bonding up to 100)



III. How to use the ALIBAVA system



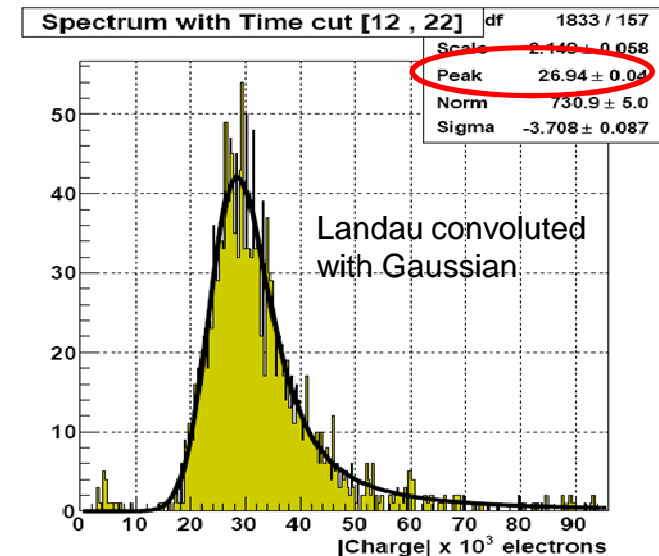
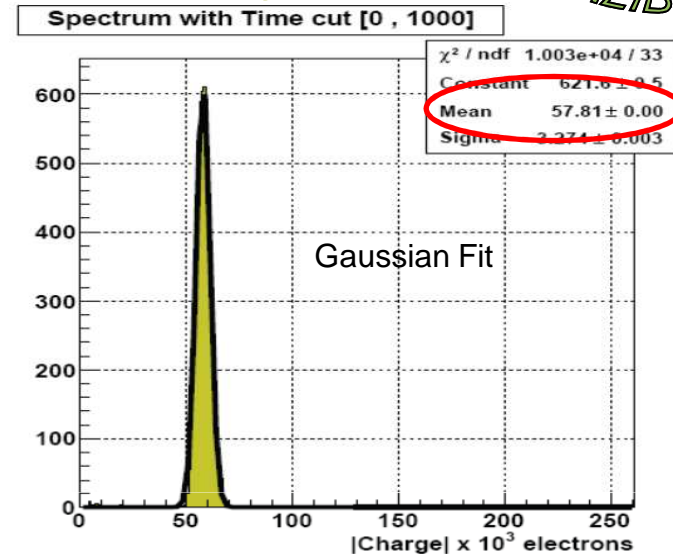
□ Laser measurements:

- Laser synchronization (laser delay in ns)
- Laser run and data analysis
(calibration and pedestals applied)

□ Radioactive source (^{90}Sr) measurements:

- Final Collected Charge-Bias Voltage curves made with the laser setup. Measurements with the beta setup are only necessary for a few bias voltage. They are used to calibrate the laser beam.
- Trigger configuration (one or two PM's, threshold ...)

□ Normalization to 24ke^- (in order to compare with other measurements)



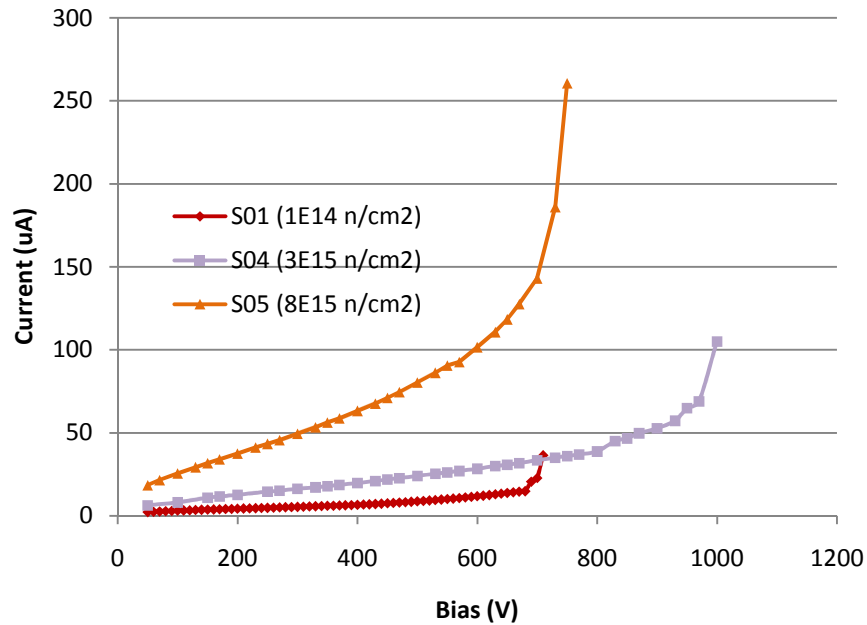
IV. Detectors

- We have measured three different wafers
 - Two with n-on-p sensors
 - One with n-on-n sensor to compare
- Each wafer has sensors irradiated with neutrons at different doses

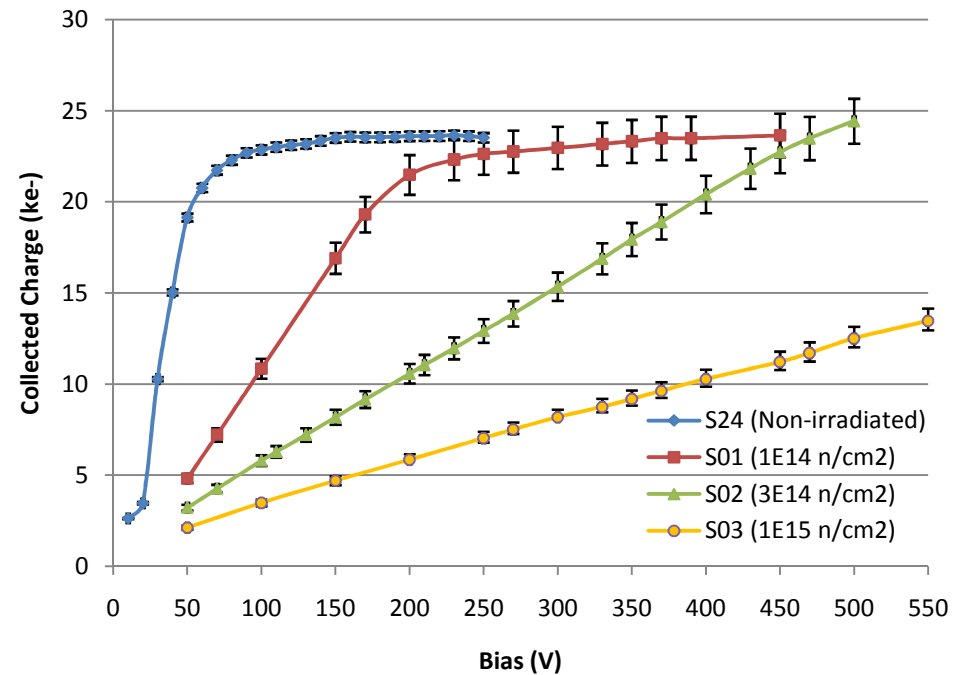
Type	Wafer	Non-irradiated	$10^{14}(\text{n/cm}^2)$	$3 \times 10^{14}(\text{n/cm}^2)$	$10^{15}(\text{n/cm}^2)$
n-on-n FZ	W17	S24	S01	S02	S03
n-on-p FZ	W04	S08	S01	S02	S03
n-on-p MCZ	W10	S21	S15	S16	S17

- ~~×~~ : we could not read out any signal
- ~~-----~~ : we could not normalise the measurements with the corresponding non irradiated sensor

IV. Detectors: Wafer 17 (n-on-n FZ) (-25°C)



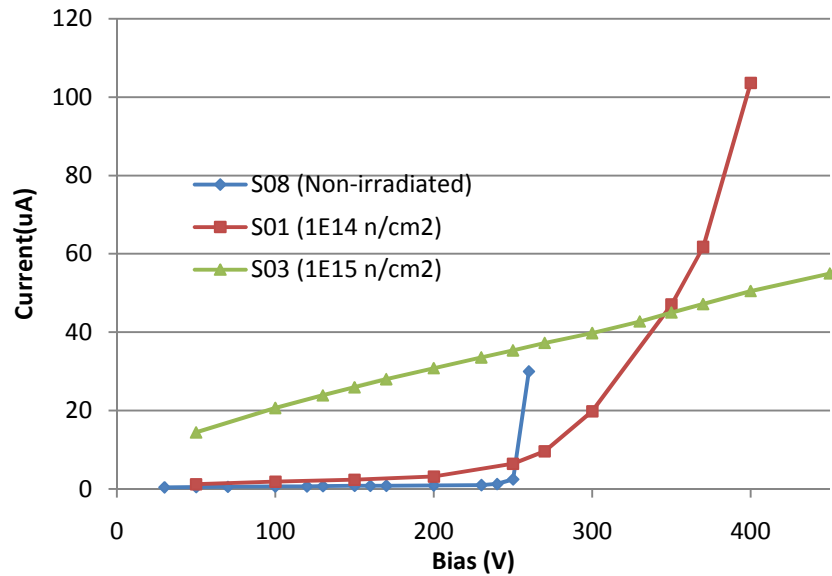
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IV Curves



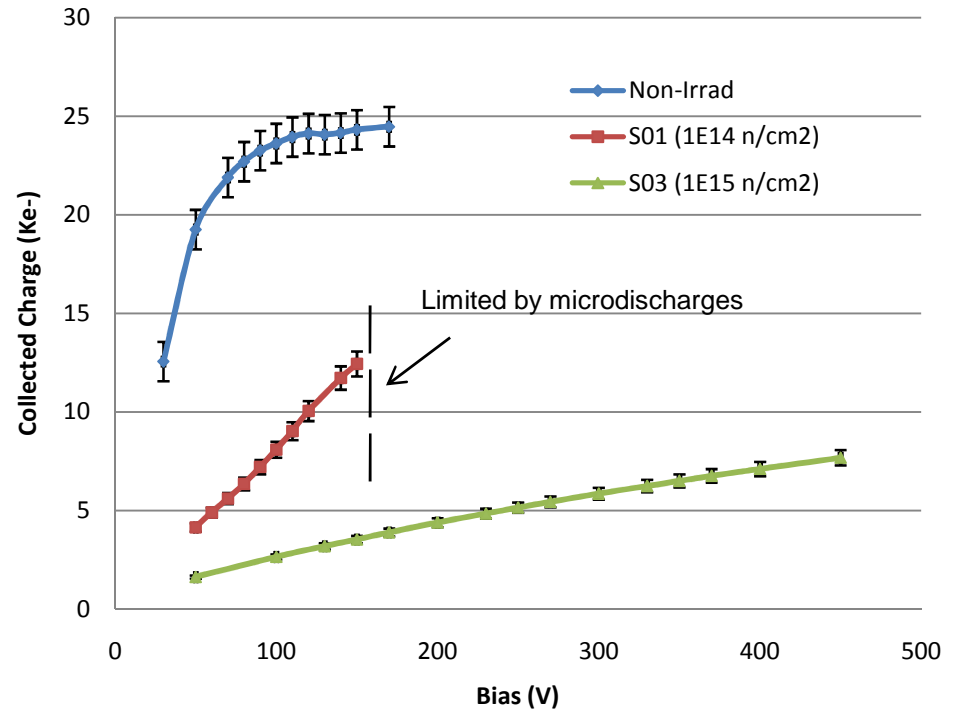
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QV Curves

IV. Detectors: Wafer 04 (n-on-p FZ) (-25°C)

(-25°C)



↑
IV Curves



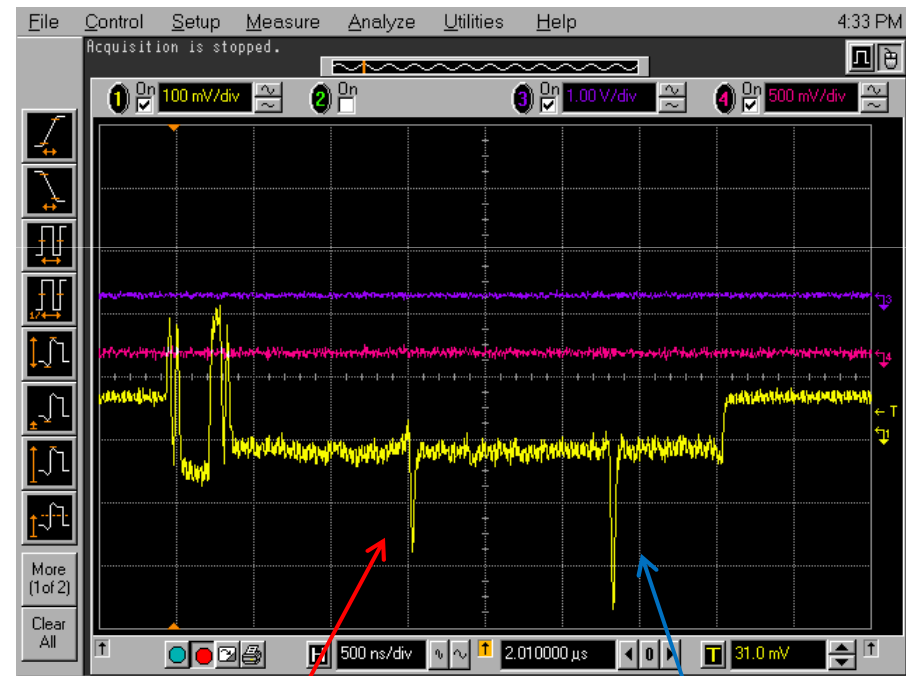
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QV Curves

V. Microdischarges

- Microdischarges have been observed in these detectors during the measurements in our setup
- They appear as high signal peaks.



Microdischarges signals

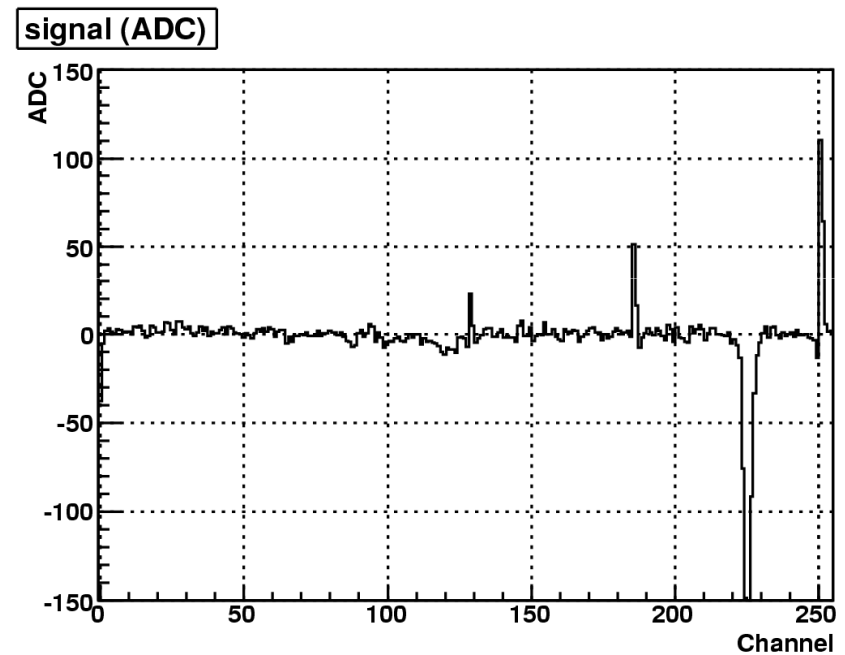
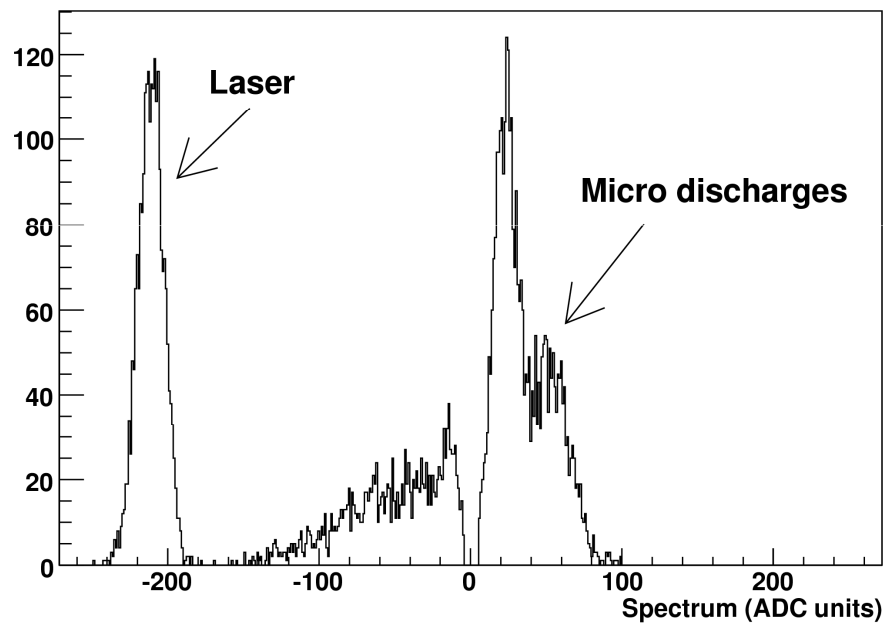


Microdischarge signal

Laser signal

V. Microdischarges

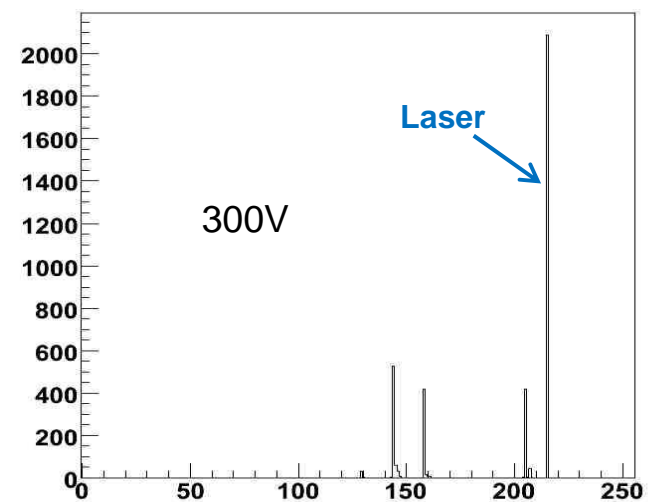
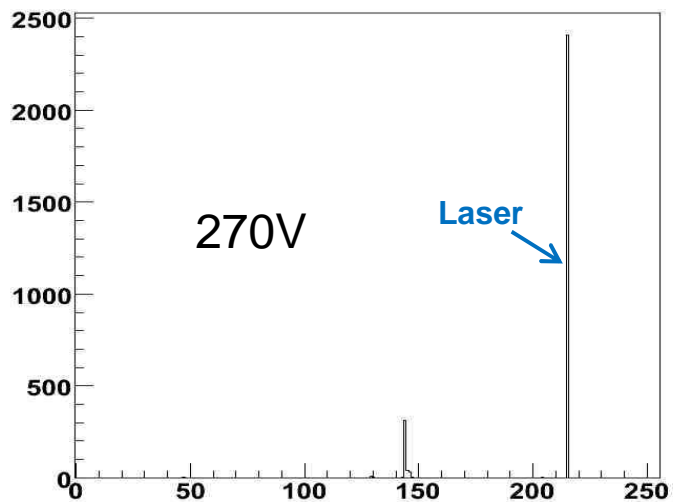
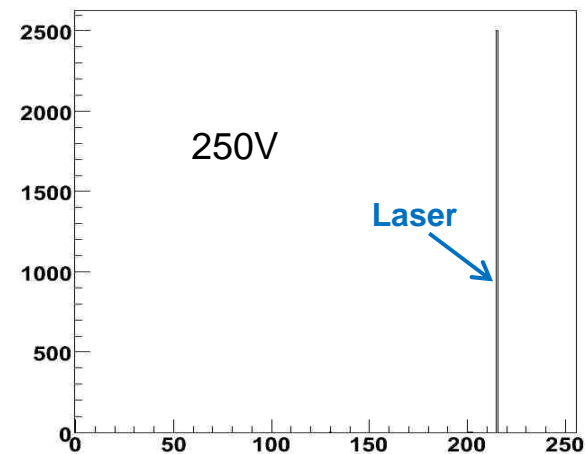
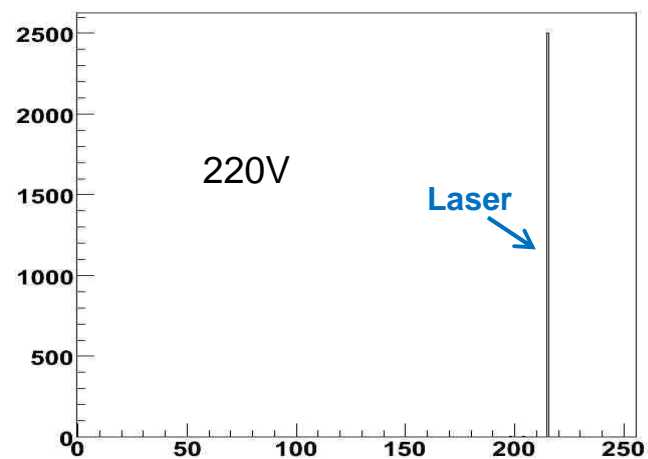
- Microdischarges can represent a problem for the beetle chip. They can burn it.
- They can have both polarities.



V. Microdischarges

S02-W04 (irradiated 3×10^{14})

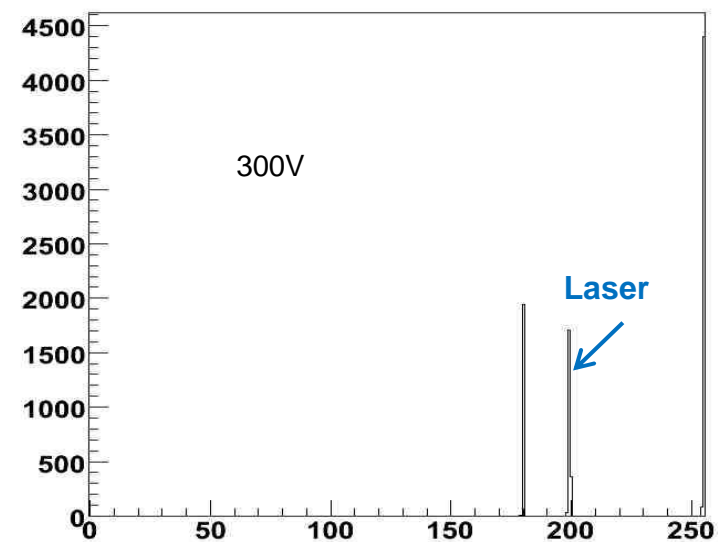
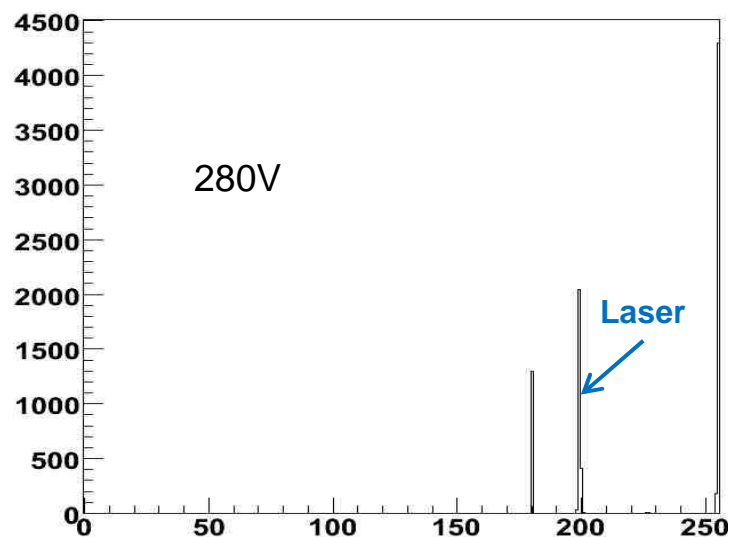
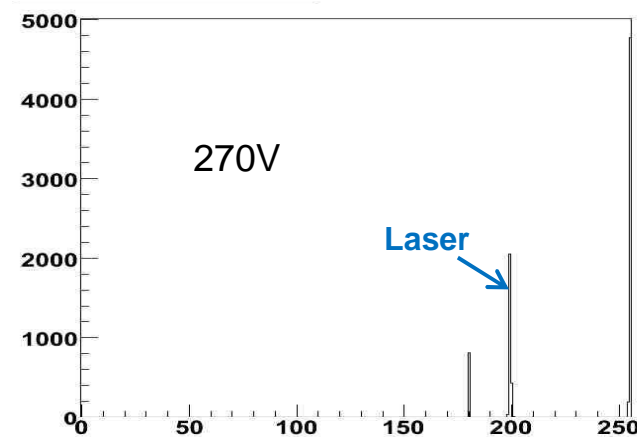
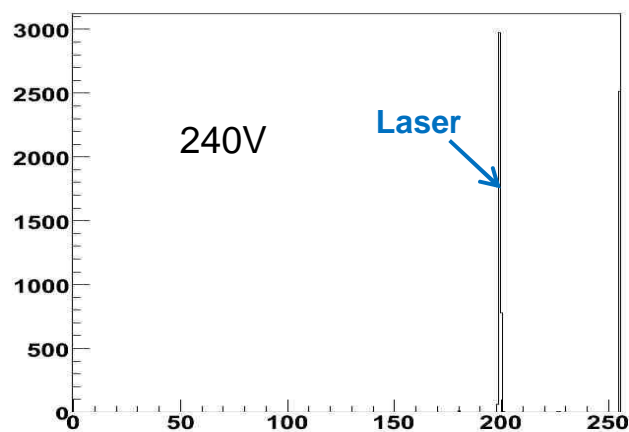
Hit Map



V. Microdischarges

S24-W17 (non-irradiated)

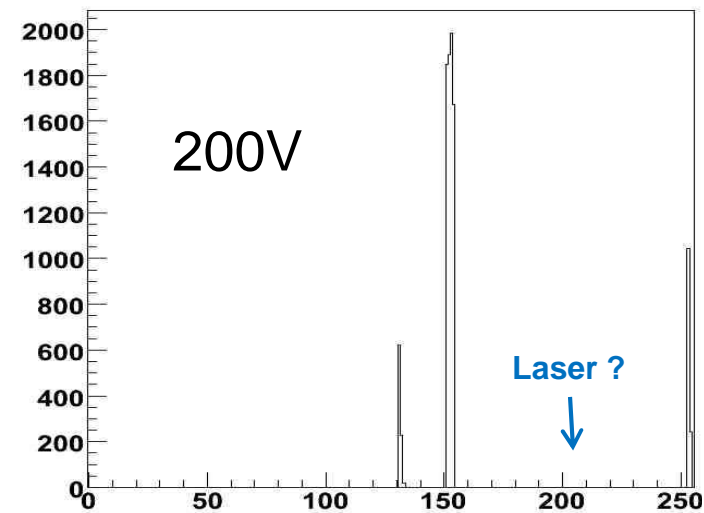
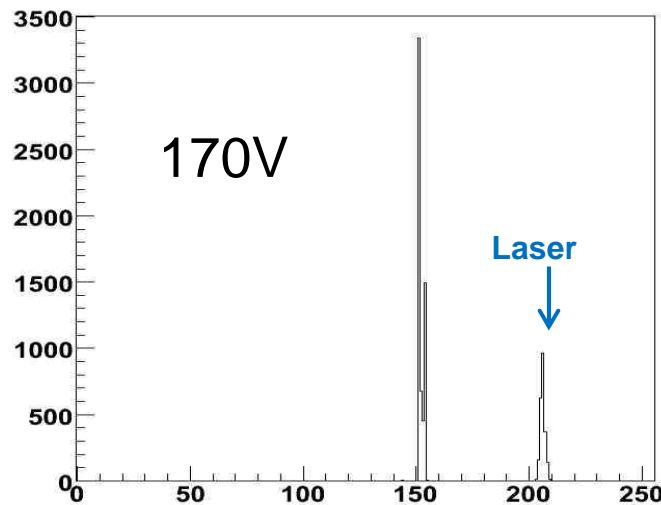
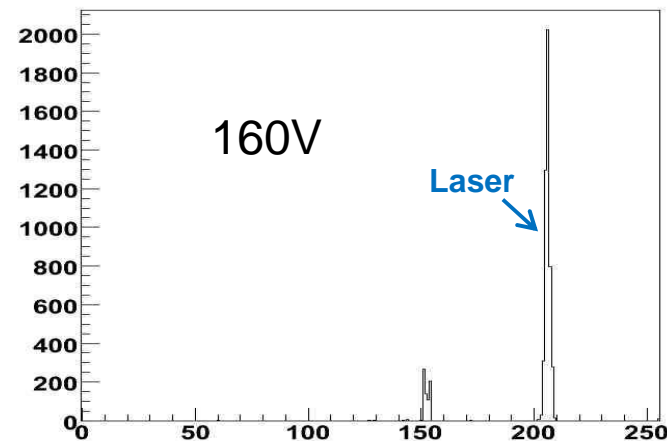
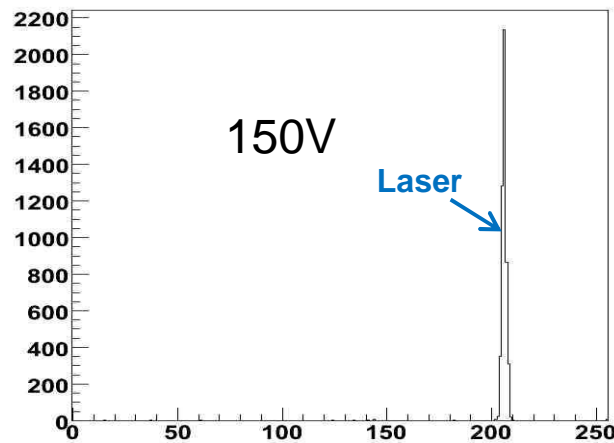
Hit Map



V. Microdischarges

S08-W04 (non-irradiated)

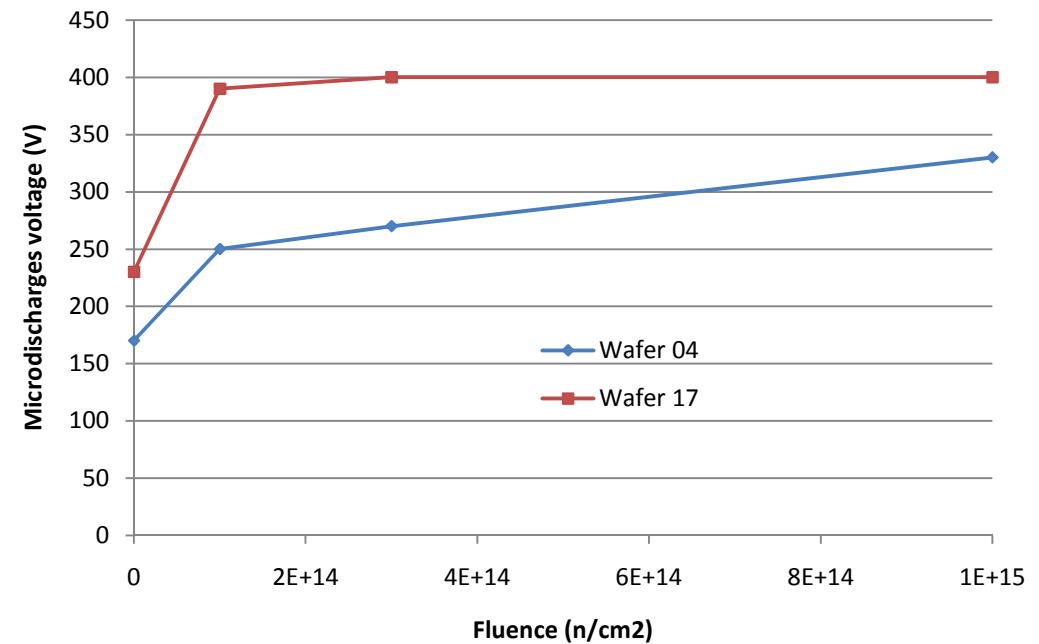
Hit Map



V. Microdischarges

- At higher fluences, the microdischarges appear later

Microdischarge Voltage (V)		
Fluence (n/cm ²)	Wafer 04 (n-on-p FZ)	Wafer 17 (n-on-n FZ)
0	170	230
1x10 ¹⁴	250	390
3x10 ¹⁴	270	400
1x10 ¹⁵	330	400



VI. Summary

- N-on-N and N-on-P microstrip silicon sensors have been measured and characterized in terms of their neutron radiation damage with the ALIBAVA system.
- Measurements limited by massive microdischarges
 - We need to understand Microdischarges
 - This problem comes from our setup? from the detectors?
 - Does anyone else see microdischarges with these kind of sensors?
 - What is the maximum rate we can tolerate without worrying about electronics and/or sensors?



- Thank you -

- Backup -

III. How to use the ALIBAVA system



□ Correction factors:

- Comparison between collected charge by radiation source and laser

$$R_{src} = \frac{\text{Collected Charge (source setup)}}{\text{Collected Charge (laser setup)}} \quad (\text{Non-irradiated sensor})$$

- Normalization of the radioactive source's peak at 24.000 electrons

$$R_{24} = \frac{24}{Q_{\text{mean}} (\text{source setup})} \quad (\text{Non-irradiated sensor})$$

- Temperature dependence: Use calibration at 20°C and gain correction factor (only applied to irradiated sensors)

$$R_{cal} = \frac{Q_{\text{outside}} (\text{source setup})}{Q_{\text{inside}} (\text{source setup})} \quad (\text{Non-irradiated sensor})$$

□ For laser data with irradiated detectors:

$$Q_{\text{corrected}} = R_{24} \times R_{cal} \times R_{src} \times Q_{cal}$$

- Q_{cal} is the collected charge in electrons with the calibration (ADC/electrons conversion)